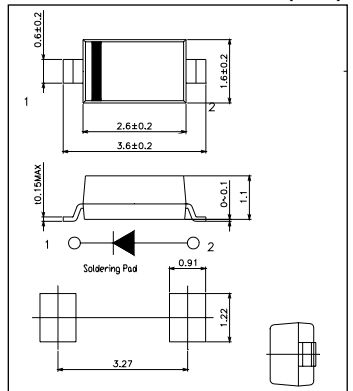


0.5A Avg. 400 Volts Standard Recovery Diode EP05DA40

■最大定格 Maximum Ratings

Item	Symbol	Conditions	Unit
くり返しピーク逆電圧 Repetitive Peak Reverse Voltage	V_{RRM}	400	V
非くり返しピーク逆電圧 Non-repetitive Peak Reverse Voltage	V_{RSM}	550	V
平均整流電流 Average Rectified Forward Current	I_O	50Hz、正弦半波通電抵抗負荷 50Hz Half Sine Wave Resistive Load	$T_a=25^{\circ}C^{*1}$ 0.38
			$T_l=107^{\circ}C$ T_l : Lead Temperature 0.5
実効順電流 R.M.S. Forward Current	$I_{F(RMS)}$	0.785	A
サージ順電流 Surge Forward Current	I_{FSM}	8 50Hz正弦半波, 1サイクル, 非くり返し 50Hz Half Sine Wave, 1cycle, Non-repetitive	A
動作接合温度範囲 Operating Junction Temperature Range	T_{jw}	-40~+150	$^{\circ}C$
保存温度範囲 Storage Temperature Range	T_{stg}	-40~+150	$^{\circ}C$

■OUTLINE DRAWING(mm)



■Approx Net Weight:0.011g

■電氣的・熱的特性 Electrical/Thermal Characteristics

Item	Symbol	Conditions	Min.	Typ.	Max.	Unit
ピーク逆電流 Peak Reverse Current	I_{RM}	$T_j=25^{\circ}C, V_{RM}=V_{RRM}$	—	—	10	μA
ピーク順電圧 Peak Forward Voltage	V_{FM}	$T_j=25^{\circ}C, I_{FM}=0.5A$	—	—	1.1	V
静電気耐量 Electrostatic Discharge	—	$T_j=25^{\circ}C, C=150pF, R=150\Omega^{*2}$	—	25	—	kV
熱抵抗 Thermal Resistance	$R_{th(j-a)}$	接合部・周囲間 *1 Junction to Ambient	—	—	300	$^{\circ}C/W$
	$R_{th(j-l)}$	接合部・リード間 Junction to Lead	—	—	70	$^{\circ}C/W$

*1: プリント基板実装 / Glass Epoxy Substrate mounted (Soldering Land=1×1mm, Both Sides)

*2: ノイズ研究所製製 ESS-630型使用、接触法 / Mesured by ESS-630S of Noise Laboratory

■定格・特性曲線

FIG.1

順電圧特性
FORWARD CURRENT VS. VOLTAGE

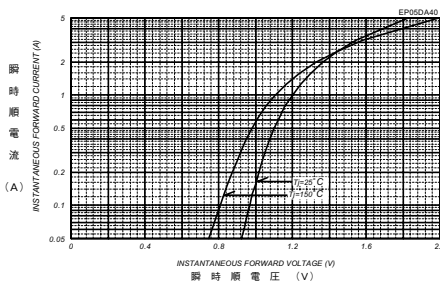


FIG.2

平均順電力損失特性
AVERAGE FORWARD POWER DISSIPATION

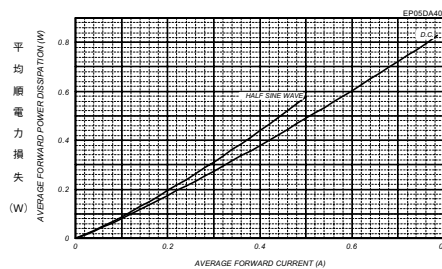


FIG.3

平均順電流 - 周囲温度定格
AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE
Glass-Epoxy Substrate Mounted (Soldering Land=1×1mm)

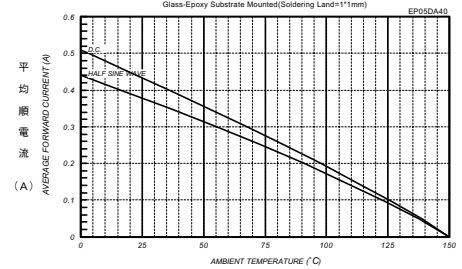


FIG.4

平均順電流 - リード温度定格
AVERAGE FORWARD CURRENT VS. LEAD TEMPERATURE

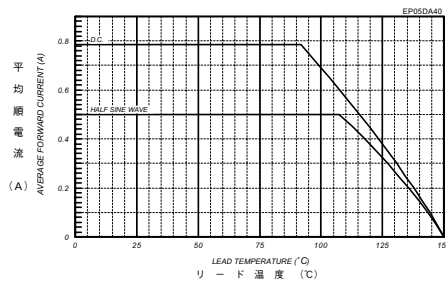


FIG.5

サージ順電流定格
SURGE CURRENT RATINGS
f=50Hz Half Sine Wave, Non-Repetitive, No Load

